

APPENDIX

1. (Amended) A platform to support [a] one or more semiconductor processing cells, comprising:
 - a lower mainframe;
 - an upper mainframe including a plurality of recesses, each one of the plurality of recesses configured to receive a semiconductor substrate processing cell; and
 - a dampener system disposed between the lower mainframe [to] and the upper mainframe.
2. (Amended) The platform of claim 1, wherein the upper mainframe further comprises a fastener structure positioned proximate each one of the recesses, wherein [the cell is affixed to] the fastener structure is configured to hold the semiconductor substrate processing cell.
3. (Amended) The platform of claim 1, wherein the upper mainframe further comprises a rigidifying plate and a main base plate[, the main base plate] comprising the plurality of recesses, the rigidifying plate comprising at least one aperture[, the rigidifying plate] and attached to the main base plate [so] such that the at least one aperture is aligned with the recesses.
4. (Amended) The platform of claim 1, wherein the semiconductor substrate processing cell is a process cell.
5. (Amended) The platform of claim 1, wherein the semiconductor substrate processing cell is a metrology cell.
6. (Amended) The platform of claim 1, wherein the semiconductor substrate processing cell is an SRD cell.

7. (Amended) The platform of claim 1, wherein the dampener system comprises a plurality of [axially extending] support members that extend between the lower mainframe and the upper mainframe.
8. (Amended) The platform of claim 7, wherein each [axially extending] support member comprises:
- a hollow tubular member;
 - a piston slidably disposed within the hollow tubular member; and
 - a dampening element contained within the hollow tubular member, wherein the piston is biased against the dampening element.
11. (Amended) A platform to support a cell, comprising:
- a lower mainframe;
 - an upper mainframe including a plurality of recesses, each one of the plurality of recesses configured to receive a cell; and
 - a dampener system connecting the lower mainframe to the upper mainframe[.], wherein the dampener system comprises a plurality of [axially extending] support members that extend between the lower mainframe and the upper mainframe, each [axially extending] support member comprises:
 - a hollow tubular member,
 - a piston slidably disposed within the hollow tubular member, and
 - a dampening element contained within the hollow tubular member,wherein the piston is biased against the dampening element.
12. (Amended) The platform of claim 11, wherein the upper mainframe further comprises a fastener structure positioned proximate each one of the recesses, wherein [the cell is affixed to] the fastener structure is configured to hold the cell.
13. (Amended) The platform of claim 11, wherein the upper mainframe further comprises a rigidifying plate and a main base plate[, the main base plate] comprising the plurality of recesses, the rigidifying plate comprising at least one aperture[, the

rigidifying plate] and attached to the main base plate [so] such that the at least one aperture is aligned with the recesses.

17. (Amended) A platform to support [a] one or more semiconductor substrate processing cells, comprising:

a lower mainframe;

an upper mainframe including a plurality of recesses, each one of the plurality of recesses configured to receive a semiconductor substrate processing cell; and

a dampener means disposed between the lower mainframe to the upper mainframe to support the upper mainframe relative to the lower mainframe.

18. (Amended) The platform of claim 17, wherein the upper mainframe further comprises a fastener [structure] means positioned proximate each one of the recesses, wherein [the cell is affixed to] the fastener [structure] means is configured to hold the semiconductor substrate processing cell.

19. (Amended) The platform of claim 17, wherein the upper mainframe further comprises a rigidifying plate and a main base plate[, the main base plate] comprising the plurality of recesses, the rigidifying plate comprising at least one aperture[, the rigidifying plate] and attached to the main base plate [so] such that the at least one aperture is aligned with the recesses.

20. (Amended) The platform of claim 17, wherein the dampener means comprises a dampening element, the dampening element [is] being sand.